Manuel Carmona

List of Publications by Year
in descending order

23 papers	319 citations	1163117 8 h-index	996975 15 g-index
23 all docs	23 docs citations	23 times ranked	388 citing authors

#	Article	IF	Citations
1	Subpixel real-time jitter detection algorithm and implementation for polarimetric and helioseismic imager. Journal of Astronomical Telescopes, Instruments, and Systems, 2019, 5, 1.	1.8	1
2	APS fixed pattern noise modelling and compensation. , 2016, , .		1
3	Design and test of a tip-tilt driver for an image stabilization system. , 2016, , .		2
4	A space grade camera for image correlation. , 2015, , .		1
5	Electronics design for a high precision image stabilization system. , 2014, , .		1
6	System model of an image stabilization system. Proceedings of SPIE, 2014, , .	0.8	7
7	Finite Element Analysis of Electrically Excited Quartz Tuning Fork Devices. Sensors, 2013, 13, 7156-7169.	3.8	19
8	A micromachined thermoelectric sensor for natural gas analysis: Multivariate calibration results. Sensors and Actuators B: Chemical, 2012, 166-167, 338-348.	7.8	21
9	High flow rate microfluidic device for blood plasma separation using a range of temperatures. Lab on A Chip, 2010, 10, 211-219.	6.0	71
10	Issues in the Use of Thermal Transients to Achieve Accurate Time-Constant Spectrums and Differential Structure Functions. IEEE Transactions on Advanced Packaging, 2010, 33, 918-923.	1.6	6
11	Learning network protocols through WSN based games. , 2010, , .		0
12	Limits to the integration of filters and lenses on thermoelectric IR detectors by flip-chip techniques. Sensors and Actuators A: Physical, 2009, 149, 65-73.	4.1	18
13	A micromachined thermoelectric sensor for natural gas analysis: Thermal model and experimental results. Sensors and Actuators B: Chemical, 2008, 134, 551-558.	7.8	36
14	A Novel Micro/Nano Electromechanical Actuator with Integral Electrodes. , 2007, , .		0
15	Finite Element Modelling of Flip Chip Gold-Gold Thermocompression Bonding. Journal of Electronic Packaging, Transactions of the ASME, 2003, 125, 549-555.	1.8	6
16	Modeling the Thermal Actuation in a Thermo-Pneumatic Micropump. Journal of Electronic Packaging, Transactions of the ASME, 2003, 125, 527-530.	1.8	5
17	<title>Test structures for CMOS-compatible silicon pressure sensor reliability characterization</title>. , 2000, , .		0
18	Modelling of microsystems with analog hardware description languages. Sensors and Actuators A: Physical, 1999, 76, 32-42.	4.1	7

#	Article	IF	Citations
19	A time-domain method for the analysis of thermal impedance response preserving the convolution form. IEEE Transactions on Components and Packaging Technologies, 1999, 22, 238-244.	1.3	31
20	Design of a modular micropump based on anodic bonding. Journal of Micromechanics and Microengineering, 1997, 7, 179-182.	2.6	61
21	Simulation and Modelling of Thermo-Pneumatic Micropumps with HDLA. IFAC Postprint Volumes IPPV / International Federation of Automatic Control, 1997, 30, 171-176.	0.4	1
22	Dynamic simulations of micropumps. Journal of Micromechanics and Microengineering, 1996, 6, 128-130.	2.6	21
23	Optimization of voltage-controlled thin-film microstructures. Sensors and Actuators A: Physical, 1995, 47, 613-617.	4.1	3